



#### 2.0A SURFACE MOUNT SUPER-FAST RECTIFIER

#### **Features**

- Glass Passivated Die Construction
- Super-Fast Recovery Time For High Efficiency
- Surge Overload Rating to 50A Peak
- Ideally Suited for Automated Assembly
- Lead Free Finish/RoHS Compliant (Note 1)
- **Green Molding Compound (No Halogen and Antimony)**

#### **Mechanical Data**

- Case: SMA/SMB
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Lead Free Plating (Matte Tin Finish). Solderable per MIL-STD-202, Method 208 (e3)
- Polarity: Cathode Band or Cathode Notch
- SMA Weight: 0.064 grams (approximate)
- SMB Weight: 0.093 grams (approximate)





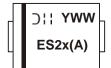
## **Ordering Information** (Note 3)

Part Number	Case	Packaging
ES2xA-13-F	SMA	5000/Tape & Reel
ES2x-13-F	SMB	3000/Tape & Reel

<sup>\*</sup> x = Device type, e.g. ES2BA-13-F (SMA package); ES2A-13-F (SMB package).

- 1. EU Directive 2002/95/EC (RoHS). All applicable RoHS exemptions applied, see EU Directive 2002/95/EC Annex Notes.
- 2. Product manufactured with Data Code 0924 (week 24, 2009) and newer are built with Green Molding Compound.
- 3. For packaging details, go to our website at http://www.diodes.com.

## **Marking Information**



ES2XA = Product type marking code, ex: ES2BA (SMA package) ES2X = Product type marking code, ex: ES2A (SMB package) □ = Manufacturers' code marking YWW = Date code marking Y = Last digit of year (ex: 2 for 2002) WW = Week code (01 to 53)

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### Maximum Ratings @TA = 25°C unless otherwise specified

Single phase, half wave, 60Hz, resistive or inductive load.

For capacitance load, derate current by 20%.

Characteristic	Symbol	ES2A/A	ES2B/A	ES2C/A	ES2D/A	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage (Note 4)	$egin{array}{c} V_{RRM} \ V_{RWM} \ V_{R} \end{array}$	50	100	150	200	V
RMS Reverse Voltage	V <sub>R(RMS)</sub>	35	70	105	140	V
Average Rectified Output Current @ T <sub>T</sub> = 110°C	Ю		2	.0		Α
Non-Repetitive Peak Forward Surge Current 8.3ms Single half Sine-Wave Superimposed on Rated Load	I <sub>FSM</sub>		5	0		Α

## **Thermal Characteristics**

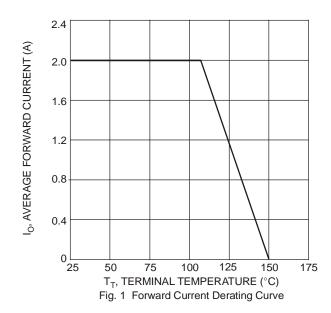
Characteristic	Symbol	Value	Unit
Typical Thermal Resistance, Junction to Terminal (Note 5)	$R_{\theta JT}$	20	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

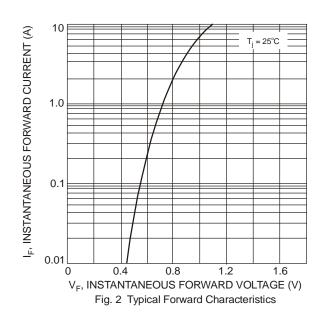
## Electrical Characteristics @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic		Symbol	Value	Unit
Forward Voltage	$@ I_F = 2.0A$	$V_{FM}$	0.92	V
Peak Reverse Current	@ T <sub>A</sub> = 25°C	I	5.0	
at Rated DC Blocking Voltage (Note 4)	@ $T_A = 125^{\circ}C$	IRM	350	μА
Typical Total Capacitance (Note 6)		C <sub>T</sub>	25	pF
Reverse Recovery Time (Note 7)		t <sub>rr</sub>	25	ns

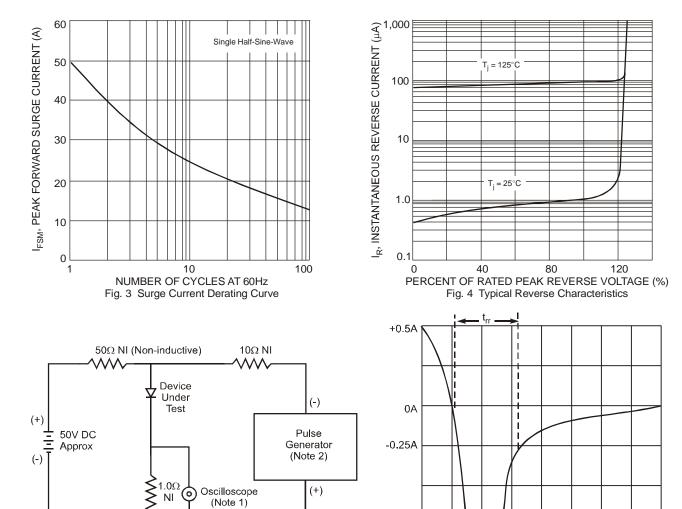
Notes:

- 4. Short duration pulse test used to minimize self-heating effect.
- 5. Unit mounted on PC board with 5.0 mm² (0.013 mm thick) copper pads as heat sink.
- 6. Measured at 1.0MHz and applied reverse voltage of 4.0V DC. 7. Measured with  $I_F=0.5A$ ,  $I_R=1.0A$ ,  $I_{rr}=0.25A$ . See Figure 5.







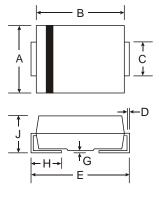


- Notes:
- 1. Rise Time = 7.0ns max. Input Impedance =  $1.0M\Omega$ , 22pF.
- 2. Rise Time = 10ns max. Input Impedance =  $50\Omega$ .

Fig. 5 Reverse Recovery Time Characteristic and Test Circuit

-1.0A

## **Package Outline Dimensions**



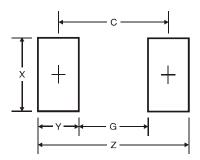
	SMA				
Dim	Min	Max			
Α	2.29	2.92			
В	4.00	4.60			
С	1.27	1.63			
D	0.15	0.31			
Е	4.80	5.59			
G	0.05	0.20			
Н	0.76	1.52			
J	2.01	2.30			
All Dim	All Dimensions in mm				

SMB				
Dim	Min	Max		
Α	3.30	3.94		
В	4.06	4.57		
С	1.96	2.21		
D	0.15	0.31		
Е	5.00	5.59		
G	0.05	0.20		
Н	0.76	1.52		
J	2.00	2.50		
All Dimensions in mm				

Set time base for 50/100 ns/cm



### **Suggested Pad Layout**



SMA Dimensions	Value (in mm)
Z	6.5
G	1.5
Х	1.7
Y	2.5
С	4.0

SMB Dimensions	Value (in mm)
Z	6.7
G	1.8
Х	2.3
Y	2.5
С	4.3

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